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United States Design Patent

Mizukoshi

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(45)

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PORTION OF A SEMICONDUCTOR DEVICE

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(75)

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(73)

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(**)

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(30)

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(51)

LOC (8) Cl.

13-03

(52)

U.S. Cl.

D13/182

(58)

Field of Classification Search

D13/182;

174/52.1, 255, 256; 257/676, 678, 691; 361/760

See application file for complete search history.

(56)

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(57)

CLAIM

The ornamental design for portion of a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of portion of a semiconductor device, showing my new design; the opposite side being a mirror image thereof;

FIG. 2 is a front elevational view thereof;

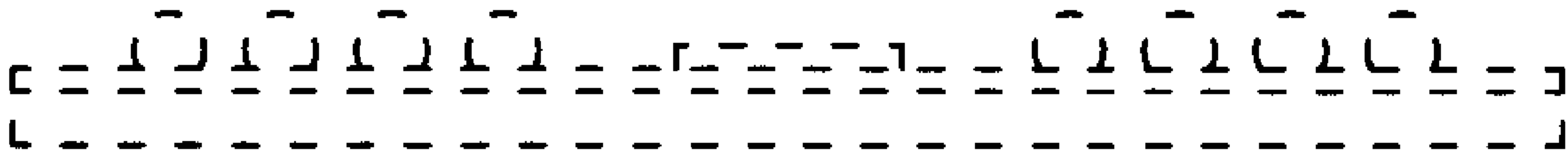
FIG. 3 is a right side elevational view thereof; the opposite side being a mirror image thereof;

FIG. 4 is a rear elevational view thereof; and,

FIG. 5 is an enlarged fragmented rear elevational view thereof, taken along the line 5—5 in FIG. 2.

The broken lines are for illustrative purposes only and form no part of the claimed design.

1 Claim, 3 Drawing Sheets



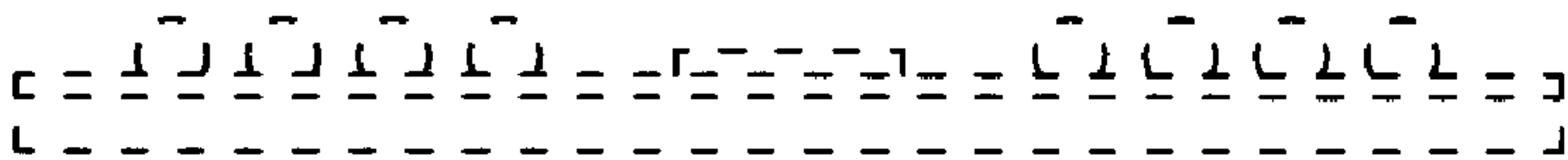


Fig.1

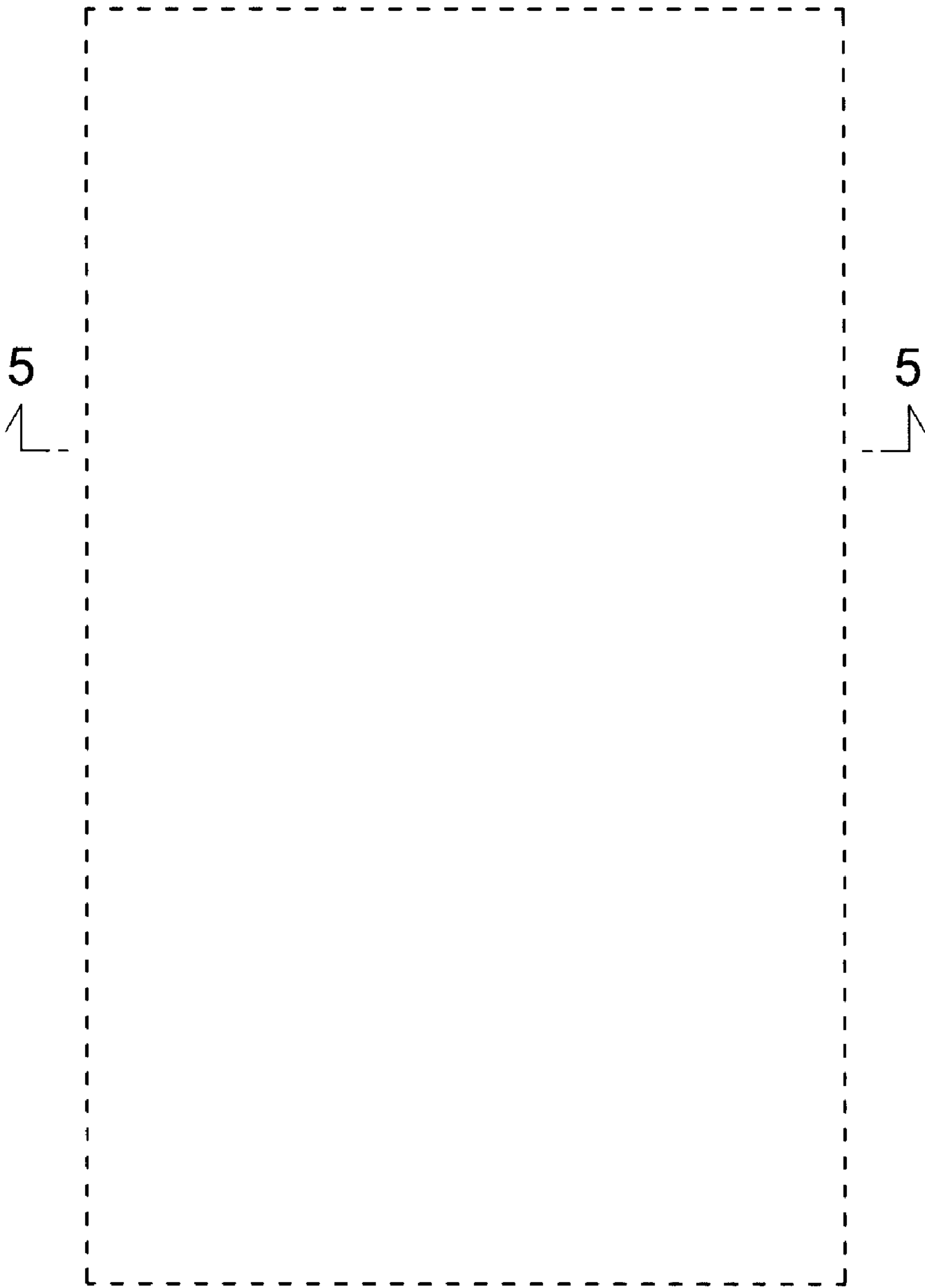


Fig.2

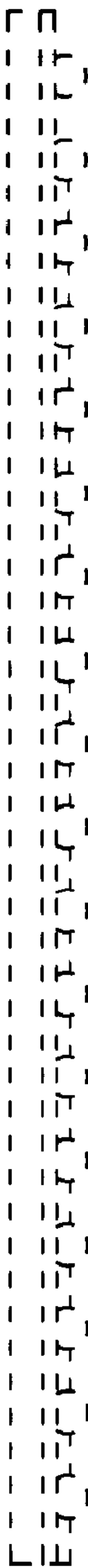


Fig.3

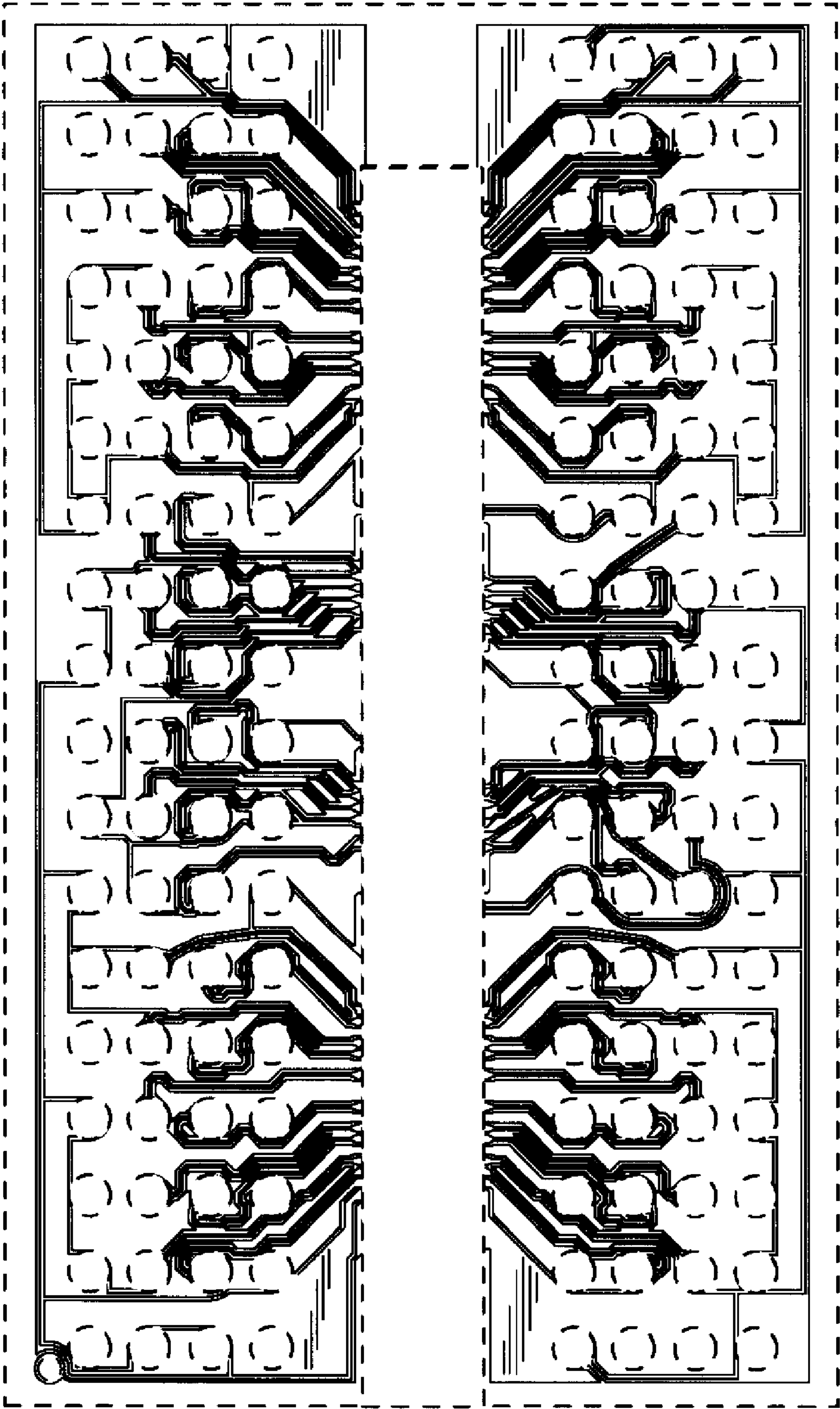


Fig.4

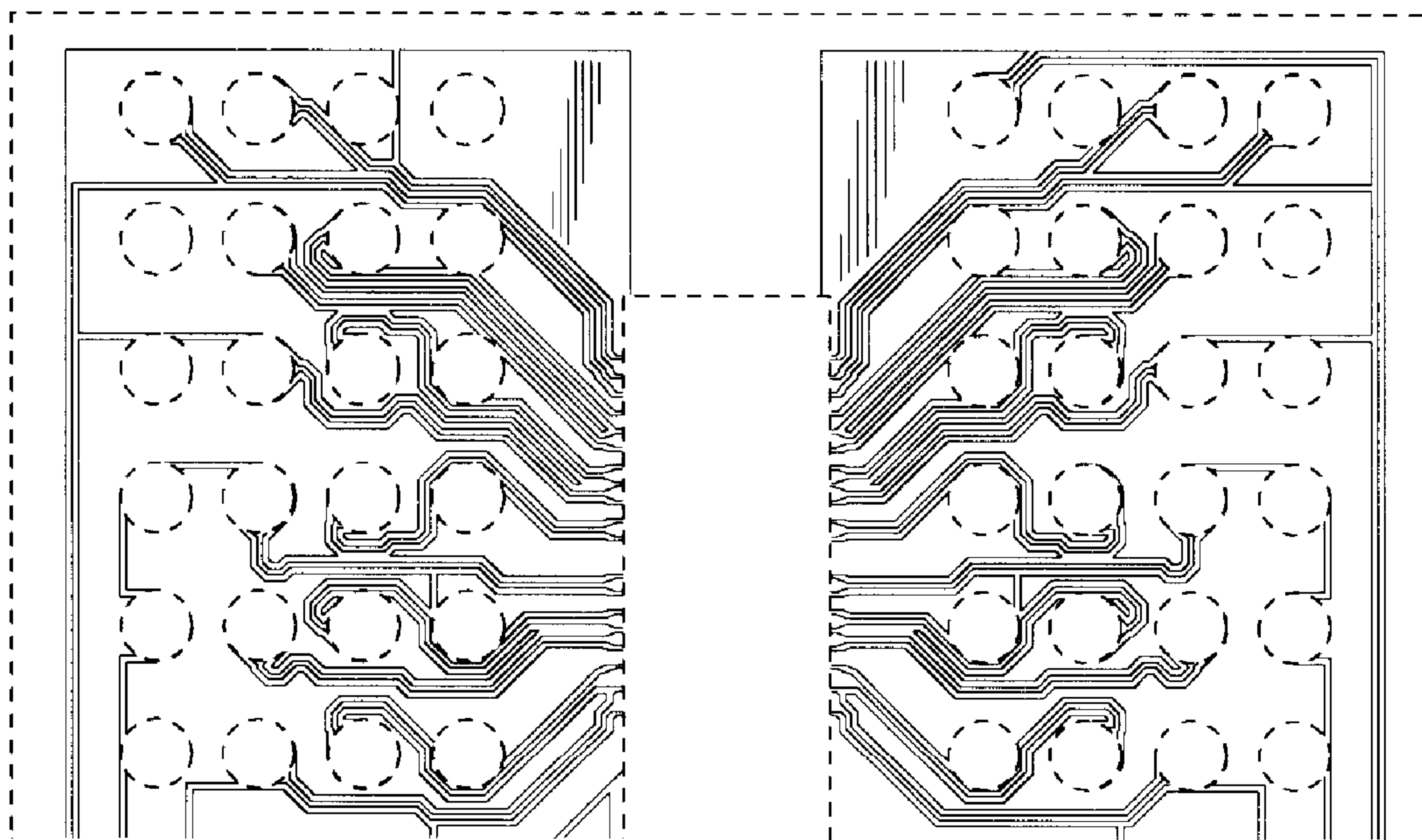


Fig.5